

semiconductor packaging news

New Multi-Functional Micro- and Nanoimprint Solution from EV Group – January 19, 2022

semiconductor packaging news

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January 19, 2022

IC Sales Growing by Double-Digits in 2022

IC Insights has updated and released its comprehensive forecast and analysis of the worldwide semiconductor industry in its January *Semiconductor Industry Flash Report*, which is included as part of the 2022, 25th edition of *The McClean Report* service. The report forecasts that the IC market will rise 11% this year following a strong 26% increase in 2021 and a 13% jump in 2020. If achieved ...



IC Insights

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Gold-coated Silver Bonding Wires

Designed to reduce the rising cost concerns. Heraeus' AgCoat Prime offers bondability & reliability of gold wires at lower cost. Click to find out more. Heraeus' AgCoat® Prime



VIEWPOINT 2022: Jeanne Beacham, Executive Chair, Delphion

2021 had its challenges for many companies across the semiconductor industry as the fall-out from the global pandemic affected everything from the supply chain to the labor pool. Increasing transportation expenses both domestically and internationally had an impact on the costs of products and materials ... Delphion Industries



Qualifying the ExposedPad TQFP for AEC-Q006 Grade 0

Semiconductor packages used in various vehicle applications require high reliability. As technological innovations in the automotive market increase, the demand for ...

Technical Paper

Intel Mum on Ohio Fab Project

Intel Corp. remains tight-lipped in response to a report that it will build a \$20 billion fab in Ohio. The largest U.S. chip maker has chosen a site in Licking County, just ...

EE Times

Technical Papers

- [Critical Considerations for Electronic Component Tin Whisker Mitigation](#)
- [Why AgCoat® Prime, why now?](#)
- [The New Technology Solutions for Advanced SIP Devices](#)
- [The Effects of Long-Term Storage on Solderability of Components](#)
- [Optimizing cycle times in the semiconductor industry with Openair-Plasma](#)
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- [High Thermal Non-Conductive Die Attach](#)

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Low moisture absorption proven to meet AEC Grade-0 and MSL Level-1 reliability. Wafer level applicable DAF. Up to 250° wire-bonding and rapid curable for ultimate productivity. AI Technology, Inc.



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Test Your Knowledge

Which planet did not lend its name to an element in The Periodic Table? See answer below.

High accuracy hybrid bonding

The automated SUSS XBS300 Hybrid Bonding Platform enables hybrid and fusion bonding of 200mm and 300mm substrates with <100 nm overlay performance. SUSS MicroTec



Press Releases

New Multi-Functional Micro- and Nanoimprint Solution from EV Group

EV Group (EVG) introduced the EVG® 7300 automated SmartNIL® nanoimprint and wafer-level optics system. The EVG7300 is the company's most advanced solution ...

EV Group

Secure Photonics Device Handling

Gel-Pak, a Delphion company, will showcase its new micro textured device carrier at Photonics West from January 25-27 in San Francisco, CA. Gel-Pak's new TXF film carrier uses ... Gel-Pak

Electronic System Design Industry Logs

17% Year-Over-Year Revenue Growth in Q3 2021

Electronic System Design (ESD) industry revenue increased 17.1% year-over-year from \$2,953.9 million to \$3,458.1 million in Q3 2021, the ESD Alliance, a SEMI Technology Community ...

SEMI

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[Taiwan's TSMC, MediaTek looking to add 10,000 engineers](#)

Taiwanese chipmakers Taiwan Semiconductor Manufacturing Co (TSMC) and MediaTek are looking to hire more than 10,000 engineers in total this year. Sources told Nikkel ...

Taiwan News

[Is the world still too dependent on Asia to solve the chip shortage?](#)

Last year, at the peak of the global chip shortage, we discussed if the world's too dependent on Asia for its chip supplies. After all, the region has been the world's biggest ...

Techwire Asia

[EyeQ Ultra is Mobileye's latest SoC for autonomous driving](#)

Mobileye announced its EyeQ Ultra system-on-chip at CES, it's most advanced EyeQ version to date according to the company. Described as a single package AV-on-chip ...

EE Times



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[Arm Predicts Stagnation if Nvidia Deal Falls](#)

Arm faces significant hurdles to growth as a standalone company if Nvidia's proposed acquisition falls through, according to documents released as part of the U.K. ...

EE Times

[Manufacturing Bits: Jan. 18](#)

CERN, the European Organization for Nuclear Research, has made a breakthrough in particle physics by conducting the world's most precise measurements and ...

Semiconductor Engineering

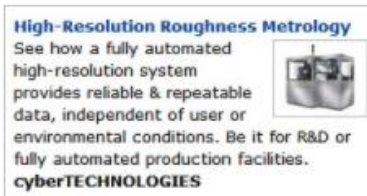
[Power-Performance Bits: Jan. 18](#)

Researchers from the University of Arizona created a 3D printed wearable that can operate continuously through wireless power to track body temperature and muscle ...

Semiconductor Engineering



Die-to-wafer Bonding Accelerates Heterogeneous Integration
Flexible hybrid bonding technologies are key to speeding up the deployment of HI. This white paper reviews different D2W bonding approaches.
EV Group



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Quote of the Day

Success seems to be largely a matter of hanging on after others have let go.

William Feather

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Circuit Technology Center



What Year Was It?

[Edgar Allan Poe is Born](#)

Poet, author and literary critic Edgar Allan Poe is born in Boston, Massachusetts.

[The day was Jan 19. What year was it?](#)



Plasma Treatment during FOWLP Optimizes Performance and Costs

Fan-out Wafer-Level (FOWLP) & Fan-out Panel-Level (FOPLP) benefit from plasma treatment, which ensures

surfaces are contamination-free. Read more

MARCH | Nordson Electronics Solutions



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[TSMC raises the bar with record capital spending](#)

Taiwan's TSMC has announced the largest annual capital spending budget of any company in the history of the semiconductor industry. The world's largest integrated ...

Asia Times

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Cartoon of the Day



"Everyone laughed and called me a fool, but I've spent the past 30 years watching my helium stocks go up!"

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Amkor's Double Sided Molded BGA Solutions

To improve the integration of RFFE solutions, Amkor offers a DSMBGA package that allows molded assembly of components on both sides of the substrate. **Amkor Technology, Inc.**



Test Your Knowledge Answer

Which planet did not lend its name to an element in The Periodic Table?

Answer: Saturn

[NEWSLETTER ARCHIVES](#)

Calendar

- [Jan 20, 2022: Overview of Semiconductor Manufacturing for American Attendees](#)
- [Jan 31, 2022: Pan Pacific Microelectronics Symposium](#)
- [Feb 3, 2022: Overview of Semiconductor Manufacturing webinar for American Attendees](#)
- [Feb 9, 2022: SEMICON Korea 2022 Hybrid](#)

Die-to-wafer Bonding Accelerates Heterogeneous Integration

Flexible hybrid bonding technologies are key to speeding up the deployment of HI. This white paper reviews different D2W bonding approaches.



EV Group

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See how a fully automated high-resolution system provides reliable & repeatable data, independent of user or environmental conditions. Be it for R&D or fully automated production facilities.



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